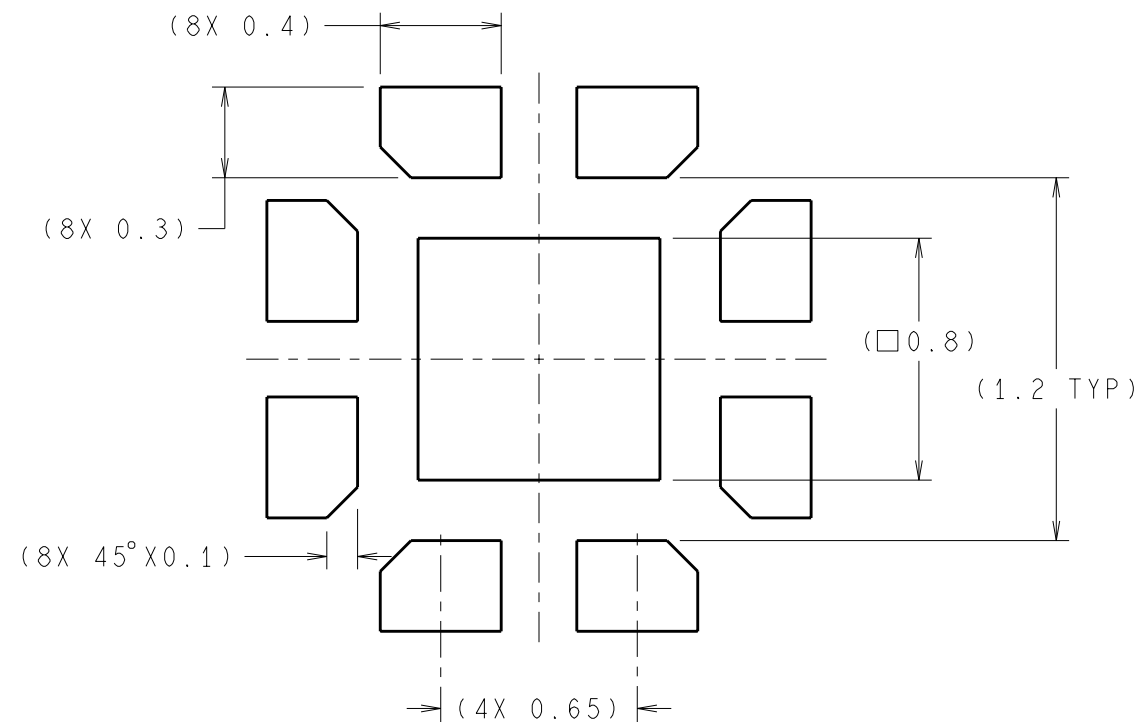
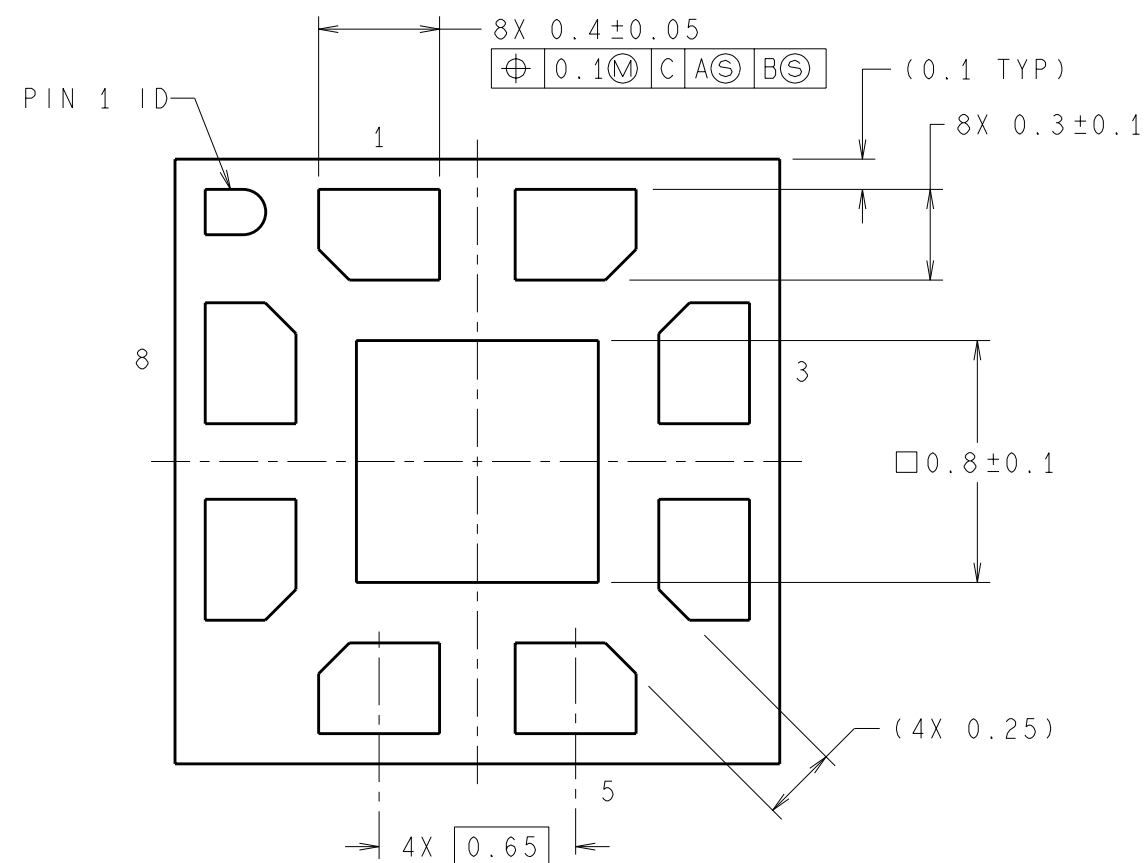
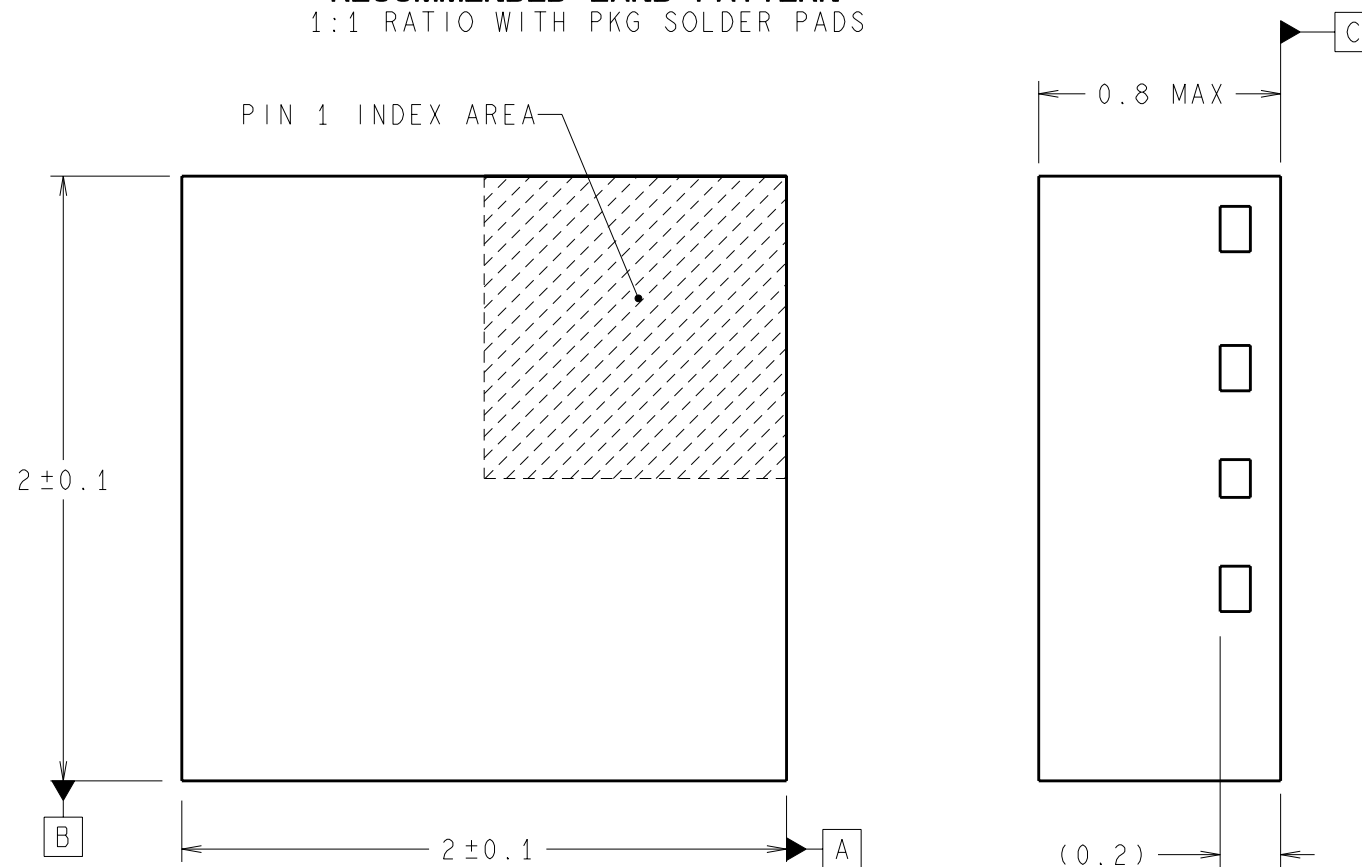




DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM OF TIN/LEAD SOLDER ON COPPER.
- NO JEDEC REGISTRATION AS OF NOVEMBER 2002.

REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	807	09/10/2002	TL/JB
B	NOTE 1: 5.08 MICROMETERS WAS 35 MICRONS; UPDATE NOTE 2	879	11/20/2002	TL/JB

APPROVALS		DATE		 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	T. LEQUANG		09/10/2002	
DFTG. CHK.	MARTA SUCHY		11/20/2002	LLP, PLASTIC, QUAD, 2x2x0.75 mm BODY, 8 LD, 0.65 mm PITCH
ENGR. CHK.	JAIME BAYAN		11/20/2002	
PROJECTION		SCALE	SIZE	DRAWING NUMBER
 MM		NTS	B	(SC)MKT-LQB08A
FORMERLY: N/A		SHEET 1 of 1		REV
				B